

Features

- 650-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives



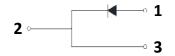


Part Number	Package	Marking
HC3D20065A	TO-220C-2L	HC3D20065A

Maximum Ratings ($T_c = 25 \, ^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
V _{RRM}	Repetitive Peak Reverse Voltage	650	٧	
V _{RSM}	Surge Peak Reverse Voltage	650	٧	
V _{DC}	DC Blocking Voltage	650	٧	
I _F	Continuous Forward Current	20	А	T _c =125°C
I _{FRM}	Repetitive Peak Forward Surge Current	81	А	T _c =110°C, t _p =10 ms, Half Sine Wave
I _{FSM}	Non-Repetitive Peak Forward Surge Current	123 104	А	T_c =25°C, t_p = 10 ms, Half Sine Wave T_c =150°C, t_p = 10 ms, Half Sine Wave
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	450	А	T_c =25°C, t_p = 10 μ s, Pulse
P _{tot}	Power Dissipation	115	w	T _c =25°C
T_J , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	°C	





Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions
V _F	Forward Voltage	1.35 1.5	1.5 -	V	I _F = 20 A ,T _J =25°C I _F = 20 A ,T _J =175°C
I _R	Reverse Current	0.06 12	100 -	μА	V _R = 650 V T _J =25°C V _R = 650 V T _J =175°C
Q _c	Total Capacitive Charge	24		nC	$V_R = 400 \text{ V, I}_F = 10 \text{ A}$ $di/dt = 500 \text{ A}/\mu\text{s}$ $T_J = 25^{\circ}\text{C}$
С	Total Capacitance	1000 91		pF	V _R = 0 V, T _J = 25°C, f = 1 MHz V _R = 400 V, T _J = 25°C, f = 1 MHz
E _{ava}	Non-repetetive Avaranche Energy	220		mJ	L=1mH

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit
$R_{_{\theta JC}}$	Thermal Resistance from Junction to Case	0.87	°C/W

Typical Performance

Fig.1 V_F - I_F Characteristics

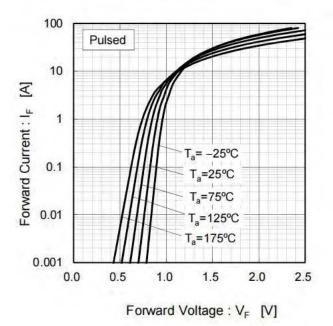
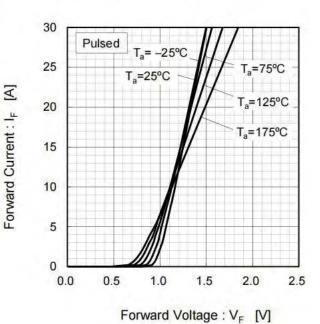
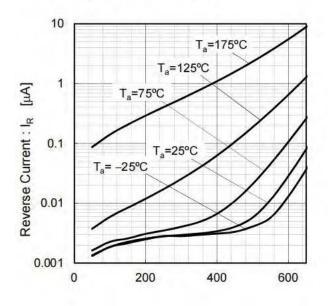


Fig. 2 V_F - I_F Characteristics



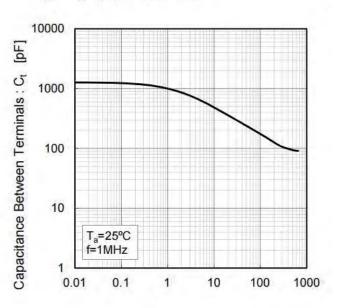
Typical Performance

Fig. 3 V_R - I_R Characteristics



Reverse Voltage : V_R [V]

Fig.4 V_R-C_t Characteristics



Reverse Voltage : V_R [V]

Fig.5 Typical Transient Thermal Resistance vs. Pulse Width

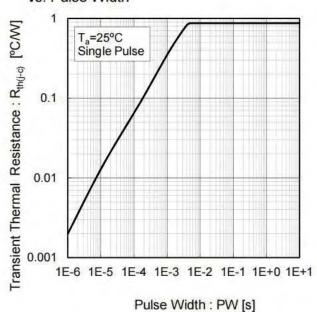
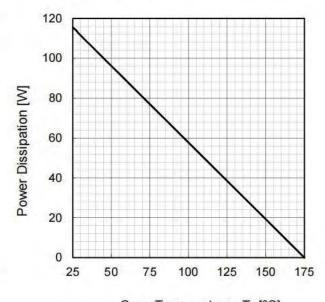


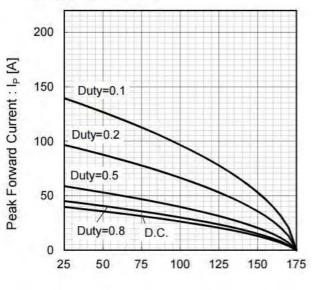
Fig.6 Power Dissipation



Case Temperature : T_c [°C]

Typical Performance

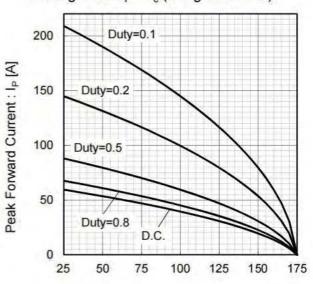
Fig.7*3 Maximum peak forward current derating curve $I_P - T_c$



Case Temperature : T_c [°C]

*3 Based on max Vf, max R_{th(j-c)} Valid for switching of above 10kHz, excluding D.C. curve.

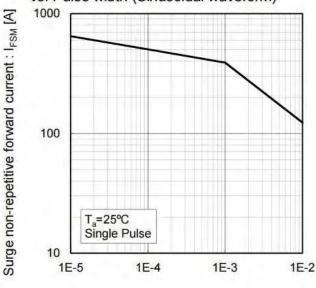
Fig.8*4 Typical peak forward current derating curve I_P - T_c (Not guaranteed)



Case Temperature : T_c [°C]

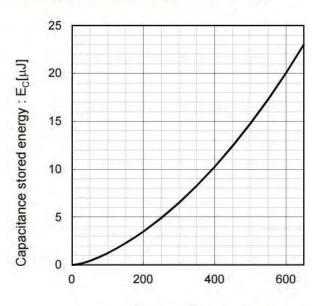
*4 Based on typ Vf, typ R_{th(j-c)} Typical value, not guaranteed Valid for switching of above 10kHz, excluding D.C. curve

Fig.9 Surge non-repetitive forward current vs. Pulse width (Sinusoidal waveform)

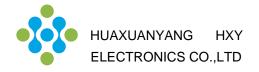


Pulse Width: PW[s]

Fig. 10 Typical capacitance store energy



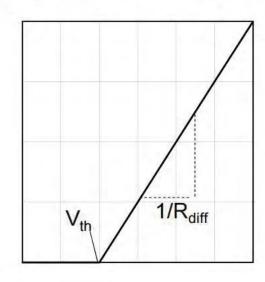
Reverse Voltage : V_R [V]



Typical Performance

Forward Current : I_F

Fig.11 Equivalent forward current curve



Forward Voltage: V_F

$$V_F = V_{th} + R_{diff}I_F$$

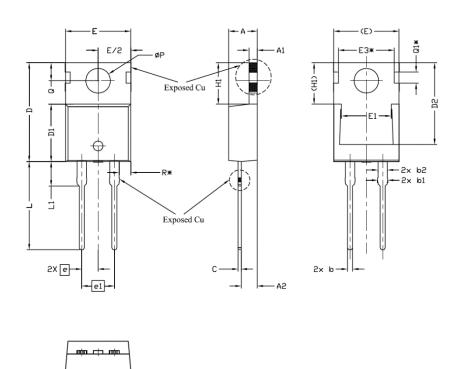
$$V_{th}(T_j) = a_0 + a_1 T_j$$

 $R_{diff}(T_j) = b_0 + b_1 T_j + b_2 T_j^2$

Symbol	Typical Value	Unit
a_0	9.66E-01	V
a ₁	- 1.10E-03	V/°C
b _o	1.76E-02	Ω
b ₁	3.73E-05	Ω/°C
b ₂	3.84E-07	$\Omega / ^{\circ}C^{2}$

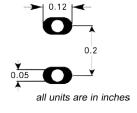
 T_j in °C; -55 °C < T_j < 175°C ; I_F < 40A

Package Information TO-220C-2L

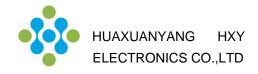


		DIMENSION:		
SYMBOL	[NOTES		
OTWIBOL	MIN.	NOM.	MAX.	HOTES
Α	4.24	4.44	4,64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9.02	
D2	12.43	12.73	12.83	5
E	9.96	10.16	10.36	4,5
E1	E1 6,86		8,89	5
E3*		8.70REF.		
е	2,54BSC			
e1		5.08BSC		
H1	6.30	6.45	6.60	5,6
L	13.47	13.72	13.97	
L1	3.60	3.80	4.00	
ØP	3.75	3.84	3.93	
Q	2,60	2,80	3,00	
Q1*	1.73REF.			
R*	1.82REF.			

Recommended Solder Pad Layout



T0220-2L



Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc.

 When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.